Elasticity (and other useful things to know)

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* With thanks to Steve Senturia, from whose lecture notes some of these materials are adapted.

Outline

- > Overview
- > Some definitions
 - Stress
 - Strain
- > Isotropic materials
 - Constitutive equations of linear elasticity
 - Plane stress
 - Thin films: residual and thermal stress
- > A few important things
 - Storing elastic energy
 - Linear elasticity in anisotropic materials
 - Behavior at large strains
- > Using this to find the stiffness of structures

Why we care about mechanics

Mechanics makes up half of the M's in MEMS!

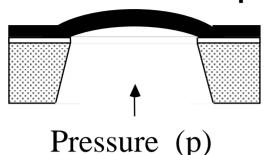


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Pressure sensors

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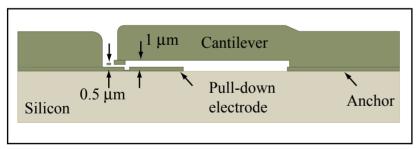


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Adapted from Rebeiz, Gabriel M. *RF MEMS: Theory, Design, and Technology.* Hoboken, NJ: John Wiley, 2003. ISBN: 9780471201694.



Veeco.com

AFM cantilevers

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Switches Zavracky et al., Int. J. RF Microwave CAE, 9:338, 1999, via Rebeiz RF MEMS

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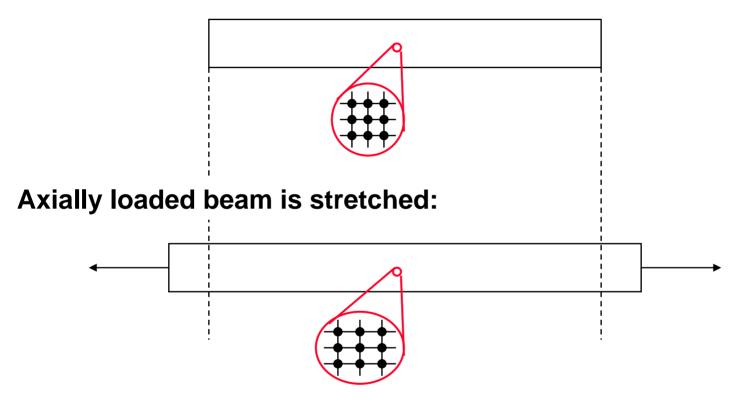
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What do we need to calculate?

- > Eager beaver suggestion: everything
 - When I apply forces to this structure, it bends.
 - Here's the function that describes its deformed shape at every point on the structure when the deformations are small.
 - Here are numerical calculations of the shape at every point on the structure when the deformations are large.
 - The structure is stressed, and the stress at every point in the structure is...
- > Shortcut suggestion: just what we really need to know
 - When I apply a force F to the structure, how far does the point of interest (the end, the middle, etc) move?
 - This boils down to a stiffness, as in F = kx
 - What is the stress at a particular point of interest (like where my sensors are, or at the point of maximum stress)?
 - How much load can I apply without breaking the structure?

Why things have stiffness I

Unloaded beam is undeformed:



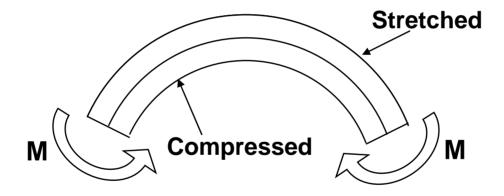
Stretching costs energy, which is stored as elastic energy. Exactly how much energy is determined by material and geometry.

Why things have stiffness II

Unloaded beam is undeformed:



Loaded beam is bent:



Stretching and compressing cost energy, which is stored in elastic energy. Exactly how much energy is determined by material and geometry.

Example: relating load to displacement in bending

What are the loads, and where on the structure are they applied?

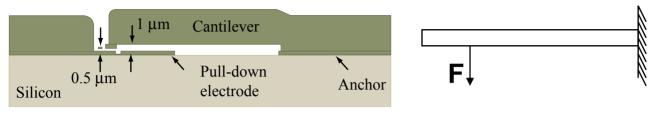
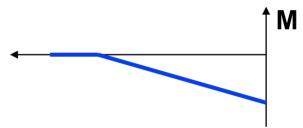


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Siven the loads, what is going on at point (x,y,z)?



- > How much curvature does that bending moment create in the structure at a given point?
 - What is the geometry of the structure?
 - What is it made of, and how does the material respond to the kind of load in question?

Elasticity

- Elasticity: the ability of a body to deform in response to applied forces, and to recover its original shape when the forces are removed
- Contrast with plasticity, which describes permanent deformation under load
- > Elasticity is described in terms of differential volume elements to which distributed forces are applied
- > Of course, all real structural elements have finite dimensions
- > We will ultimately use partial differential equations to relate applied loads and deformations

Outline

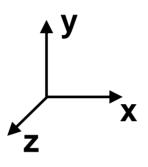
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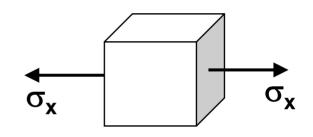
Stress

- > Stress is force per unit area
- > Normal stress

$$\sigma_x$$
, σ_y , or σ_z

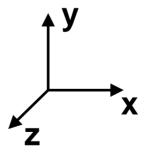
- **>** Compressive: σ < 0
- > Tensile: $\sigma > 0$

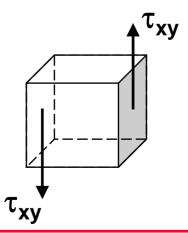




> Shear stress

$$\tau_{xy},\,\tau_{xz},\,\text{or}\,\,\tau_{yz}$$





Stress

- > Can have all components at a given point in space
- > SI Units: the Pascal
 - 1 Pascal = 1 N/m²
- > Other units:
 - 1 atm = 14 psi = 100 kPa
 - 1 dyne/cm² = 0.1 Pa
- > Notation: τ_{face,direction}

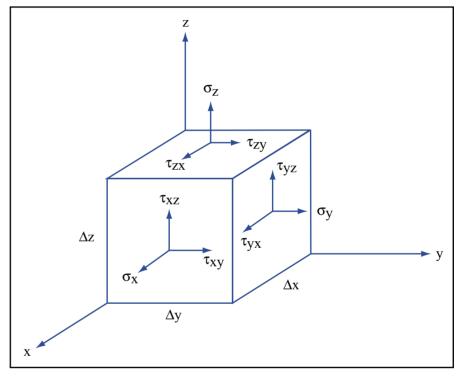


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Deformation

> Illustrating a combination of translation, rotation, and deformation

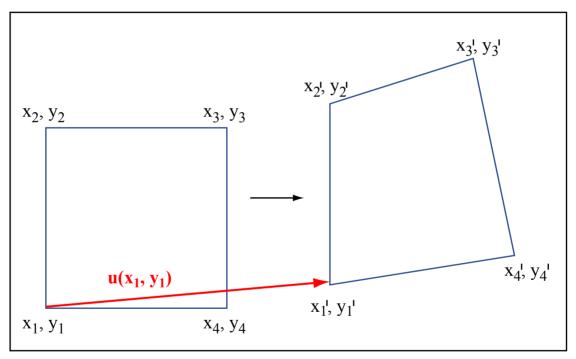


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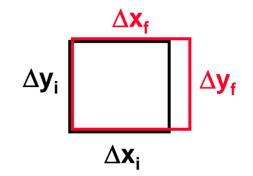
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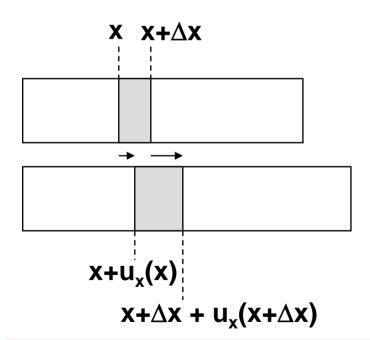
Strain

- > Strain is a continuum description of deformation.
- > Center of mass translation and rigid rotation are NOT strains
- > Strain is expressed in terms of the displacements of each point in a differential volume, u(x) where u is the displacement and x is the original coordinate
- Deformation is present only when certain derivatives of these displacements u are nonzero

Normal Strains (ε_x , ε_y , ε_z)

- > Something changes length
- Normal strain is fractional change in length (dimensionless)
- > ϵ > 0: gets longer, ϵ < 0: gets shorter





Initial length:
$$(x + \Delta x) - x = \Delta x$$

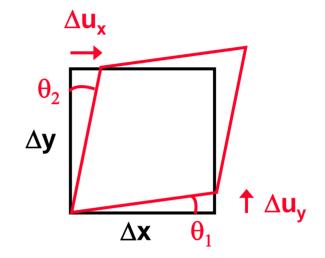
Final length:
$$(x + \Delta x + u_x(x + \Delta x)) - (x + u_x(x)) =$$

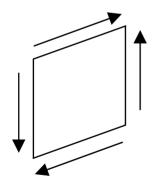
= $\Delta x + u_x(x + \Delta x) - u_x(x)$

$$\varepsilon_{x} = \frac{u_{x}(x + \Delta x) - u_{x}(x)}{\Delta x} = \frac{\partial u_{x}}{\partial x}$$

Shear Strains (γ_{xy} , γ_{xz} , γ_{yz})

- > Angles change
- Comes from shear stresses
- > Quantified as change in angle in radians





$$\gamma_{xy} = \left(\frac{\Delta u_x}{\Delta y} + \frac{\Delta u_y}{\Delta x}\right) = \left(\frac{\partial u_x}{\partial y} + \frac{\partial u_y}{\partial x}\right)$$



Different regimes

- > How are stress and strain related? It depends on the regime in which you're operating.
- > Linear vs nonlinear
 - Linear: strain is proportional to stress
 - Most things start out linear
- > Elastic vs. plastic
 - Elastic: deformation is recovered when the load is removed
 - Plastic: some deformation remains when unloaded
- > Isotropic vs. anisotropic
 - Life is simpler when properties are the same in all directions; however, anisotropic silicon is a part of life

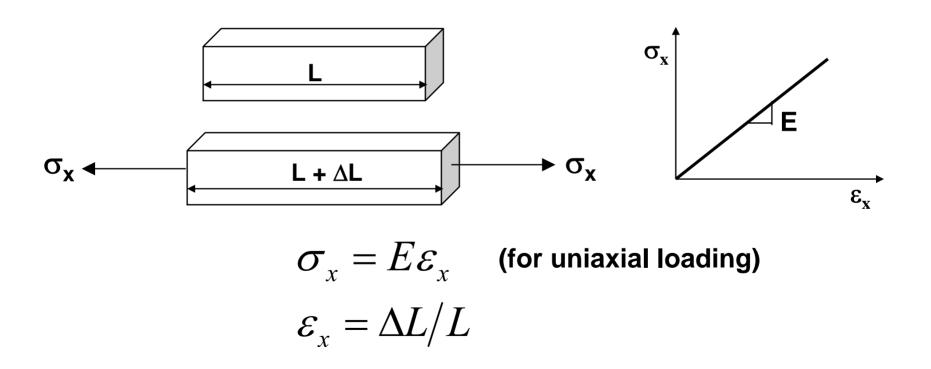
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Linear Elasticity in Isotropic Materials

> Young's modulus, E

- The ratio of axial stress to axial strain, under uniaxial loading
- Typical units in solids: GPa = 109 Pa
- Typical values 100 GPa in solids, less in polymers



Linear Elasticity in Isotropic Materials

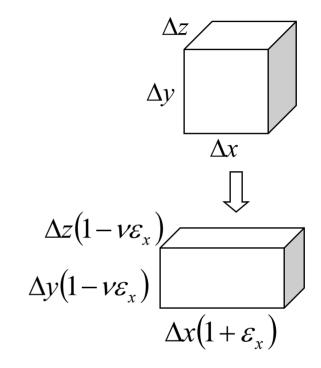
> Poisson ratio, ν

- Some things get narrower in the transverse direction when you extend them axially.
- Some things get wider in the transverse direction when you compress them axially.
- This is described by the Poisson ratio: the negative ratio of transverse strain to axial strain
- Poisson ratio is in the range 0.1 0.5 (material dependent)

$$\varepsilon_{y} = -\nu \varepsilon_{x}$$

Poisson's ratio relates to volume change

- > Volume change is proportional to (1-2v)
- > As Poisson ratio approaches ½, volume change goes to zero
 - We call such materials incompressible
- > Example of incompressible material:
 - Rubber



$$\Delta V = \Delta x \Delta y \Delta z (1 + \varepsilon_x) (1 - v \varepsilon_x)^2 - \Delta x \Delta y \Delta z$$

$$\downarrow \downarrow$$

$$\Delta V = \Delta x \Delta y \Delta z (1 - 2v) \varepsilon_x$$

Isotropic Linear Elasticity

- For a general case of loading, the constitutive relationships between stress and elastic strain are as follows
- > 6 equations, one for each normal stress and shear stress

$$\varepsilon_{x} = \frac{1}{E} \left[\sigma_{x} - \nu (\sigma_{y} + \sigma_{z}) \right]$$

$$\varepsilon_{y} = \frac{1}{G} \tau_{xy}$$

$$\varepsilon_{y} = \frac{1}{E} \left[\sigma_{y} - \nu (\sigma_{z} + \sigma_{x}) \right]$$

$$\varepsilon_{z} = \frac{1}{E} \left[\sigma_{z} - \nu (\sigma_{x} + \sigma_{y}) \right]$$

$$\gamma_{yz} = \frac{1}{G} \tau_{yz}$$

$$\gamma_{zx} = \frac{1}{G} \tau_{zx}$$

$$\gamma_{zx} = \frac{1}{G} \tau_{zx}$$

Shear modulus G is given by $G = \frac{E}{2(1+v)}$

Other Elastic Constants

- Other elastic constants in isotropic materials can always be expressed in terms of the Young's modulus and Poisson ratio
 - Shear modulus G
 - Bulk modulus (inverse of compressibility)

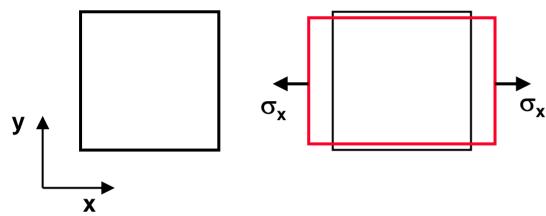
$$K = \frac{E}{3(1-2\nu)}$$

Plane stress

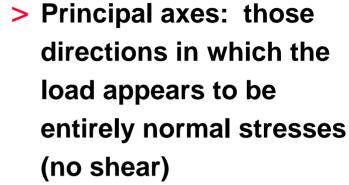
- > Special case: when all stresses are confined to a single plane Often seen in thin films on substrates (will discuss origin of these stresses shortly)
- > Zero normal stress in z direction ($\sigma_z = 0$)
- > No constraint on normal strain in z, ε_z

$$\varepsilon_{x} = \frac{1}{E} \left(\sigma_{x} - \nu \left(\sigma_{y} + \sigma_{z} \right) \right) = \frac{1}{E} \left(\sigma_{x} - \nu \sigma_{y} \right)$$
 often get insight about these from boundary conditions
$$\varepsilon_{y} = \frac{1}{E} \left(\sigma_{y} - \nu \left(\sigma_{x} + \sigma_{z} \right) \right) = \frac{1}{E} \left(\sigma_{y} - \nu \sigma_{x} \right)$$
 boundary conditions
$$\varepsilon_{z} = \frac{1}{E} \left(\sigma_{z} - \nu \left(\sigma_{x} + \sigma_{y} \right) \right) = \frac{-\nu}{E} \left(\sigma_{x} + \sigma_{y} \right)$$

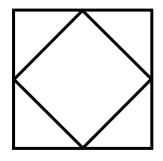
Plane stress: directional dependence

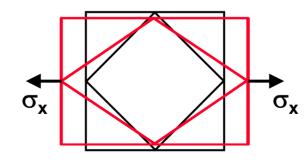


Here, principal axes are in x and y.



In general, there are shear stresses in other directions





Stresses on Inclined Sections

Can resolve axial forces into normal and shear forces on a tilted plane

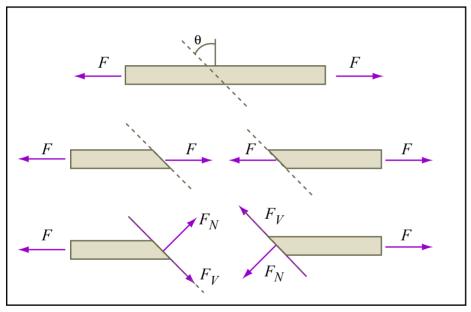


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Adapted from Figure 9.3 in: Senturia, StephenD. *Microsystem Design.* Boston, MA: Kluwer Academic Publishers, 2001, p. 205. ISBN: 9780792372462.

$$F_{N} = F \cos \theta$$

$$F_{V} = F \sin \theta$$

$$Area = \frac{A}{\cos \theta}$$

$$\sigma_{\theta} = \frac{F}{A} \cos^{2} \theta$$

$$\tau_{\theta} = \frac{F}{A} \cos \theta \sin \theta$$

Resultant stresses vary with angle

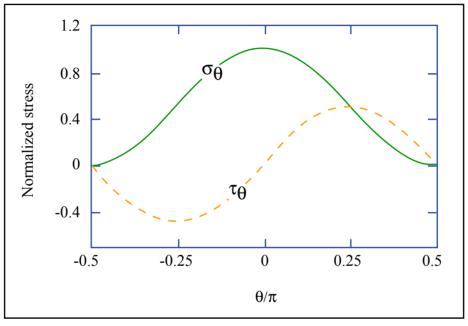


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Adapted from Figure 9.4 in Senturia, Stephen D. *Microsystem Design*. Boston, MA: Kluwer Academic Publishers, 2001, p. 206. ISBN: 9780792372462.

Failure in shear occurs at an angle of 45 degrees

Special case: biaxial stress

- > A special case of plane stress
 - Stresses σ_x and σ_v along principal axes are equal
 - Strains ε_x and ε_v along principal axes are equal
- > Leads to definition of biaxial modulus

$$\varepsilon_{x} = \frac{1}{E} (\sigma_{x} - v\sigma_{y})$$

$$\varepsilon = \frac{1}{E} (1 - v)\sigma$$

$$\varepsilon_{y} = \frac{1}{E} (\sigma_{y} - v\sigma_{x})$$

$$\sigma = \frac{E}{(1 - v)} \varepsilon$$
Biaxial modulus $= \frac{E}{(1 - v)}$

Thin Film Stress

- > A thin film on a substrate can have residual stress
 - Intrinsic stress
 - Thermal stress
- Mostly well-described as a plane stress

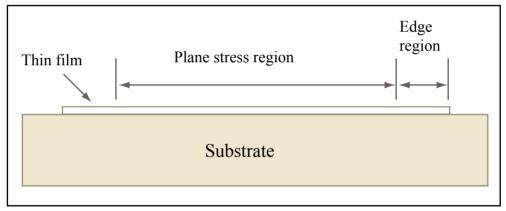


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Types of strain

- > What we have just talked about is elastic strain
 - Strains caused by loading; returns to undeformed configuration when load is removed
 - Described by the isotropic equations of linear elasticity
- > There are other kinds of strain as well
 - Thermal strain, which is related to thermal expansion
 - Plastic strain: if you stretch something too far, it doesn't return to its undeformed configuration when the load is removed (permanent component)
 - Total strain: the sum of all strains

Thermal expansion

- Thermal expansion: if you change an object's temperature, its length changes
- > This is a thermally-induced strain
- An unopposed thermal expansion produces a strain, but not a stress
- If you oppose the thermal expansion, there will be a stress
- > Coefficient of thermal expansion, $\alpha_{\scriptscriptstyle T}$

$$\varepsilon_{x}^{thermal}(\Delta T) = \alpha_{T} \Delta T$$

$$\downarrow \downarrow$$

$$\varepsilon_{x}(T) = \varepsilon_{x}(T_{0}) + \alpha_{T}(T - T_{0})$$
and

$$\frac{\Delta V}{V} = 3\alpha_T (T - T_0)$$

Thermally Induced Residual Stress

- If a thin film is adhered to a substrate, mismatch of thermal expansion coefficient between film and substrate can lead to stresses in the film (and, to a lesser degree, stresses in the substrate)
- > The stresses also set up bending moments
 - You care about this if you don't want your wafer to curl up like a saucer or potato chip
- And the vertical expansion of the film is also modified

Thermally Induced Residual Stress

Substrate:

$$\varepsilon_s = -\alpha_{T,s} \Delta T$$
where
$$\Delta T = T_d - T_r$$

Film:

$$\varepsilon_{f,free} = -\alpha_{T,f} \Delta T$$

$$\varepsilon_{f,attached} = -\alpha_{T,s} \Delta T$$

Some of the final strain is accounted for by the strain that the film would have if it were free. The remainder, or mismatch strain, will be associated with a stress through constitutive relationships.

Mismatch: $\varepsilon_{f,mismatch} = (\alpha_{T,f} - \alpha_{T,s}) \Delta T$

Biaxial stress:

$$\sigma_{f,mismatch} = \frac{E}{(1-\nu)} \varepsilon_{f,mismatch}$$

Assuming that the film is much thinner than the substrate, the film's actual strain is whatever the substrate imposes.

Intrinsic residual stress

- Any thin film residual stress that cannot be explained by thermal expansion mismatch is called an intrinsic stress
- > Sources of intrinsic stress
 - Deposition far from equilibrium
 - Secondary grain growth can modify stresses
 - Ion implantation can produce compressive stress
 - Substitutional impurities can modify stress
 - etc....

Edge effects

> If a bonded thin film is in a state of plane stress due to residual stress created when the film is formed, there are extra stresses at the edges of these films

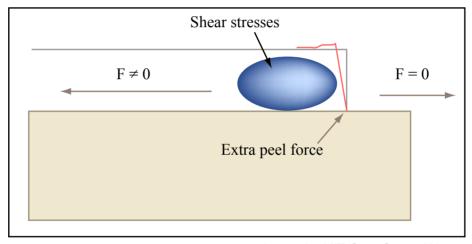


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Storing elastic energy

> Remember calculating potential energy in physics

$$U = -\int_{x_i}^{x_f} F_x dx \quad \text{(for example, } U = mgh\text{)}$$
 Deforming a material stores elastic energy

- > Stress = F/A, strain = Δ L/L

$$\int_0^{\varepsilon(x,y,z)} \sigma(\varepsilon) d\varepsilon = ???$$

> Together, they contribute 1/length³: strain energy density at a point in space

Elastic Energy

Elastic stored energy density is the integral of stress with respect to strain

Elastic energy density:
$$\widetilde{W}(x,y,z) = \int_0^{\varepsilon(x,y,z)} \sigma(\varepsilon) d\varepsilon$$

When
$$\sigma(\varepsilon) = E\varepsilon$$
: $\widetilde{W}(x,y,z) = \frac{1}{2}E[\varepsilon(x,y,z)]^2$

> The total elastic stored energy is the volume integral of the elastic energy density

Total stored elastic energy:
$$W = \iiint_{Volume} \widetilde{W}(x,y,z) dx dy dz$$

You must know the distribution of stress and strain through a structure in order to find the elastic energy stored in it (next time).

Including Shear Strains

More generally, the energy density in a linear elastic medium is related to the product of stress and strain (both normal and shear)

For axial strains:
$$\widetilde{W} = \frac{1}{2}\sigma\varepsilon$$

For shear strains:
$$\widetilde{W} = \frac{1}{2}\tau\gamma$$

This leads to a total elastic strain energy:

$$W = \frac{1}{2} \iiint_{Volume} \left(\sigma_{x} \varepsilon_{x} + \sigma_{y} \varepsilon_{y} + \sigma_{z} \varepsilon_{z} + \tau_{xy} \gamma_{xy} + \tau_{xz} \gamma_{xz} + \tau_{yz} \gamma_{yz} \right) dx dy dz$$

Linear elasticity in anisotropic materials

- > General case:
 - Stress is a second rank tensor
 - Strain is a second rank tensor
 - Elastic constants form a fourth rank tensor
- There is lots of symmetry in all the tensors
- Can represent stress as a 1 x 6 array and strain as a 1 x 6 array
- The elastic constants form a 6 x 6 array, also with symmetry

$$\begin{pmatrix} \sigma_{x} \\ \sigma_{y} \\ \sigma_{z} \\ \tau_{yz} \\ \tau_{zx} \\ \tau_{xy} \end{pmatrix} = \begin{pmatrix} C_{11} & C_{12} & C_{13} & C_{14} & C_{15} & C_{16} \\ C_{12} & C_{22} & C_{23} & C_{24} & C_{25} & C_{26} \\ C_{13} & C_{23} & C_{33} & C_{34} & C_{35} & C_{36} \\ C_{14} & C_{24} & C_{34} & C_{44} & C_{45} & C_{46} \\ C_{15} & C_{25} & C_{35} & C_{45} & C_{55} & C_{56} \\ C_{16} & C_{26} & C_{36} & C_{46} & C_{56} & C_{66} \end{pmatrix} \begin{pmatrix} \varepsilon_{x} \\ \varepsilon_{y} \\ \varepsilon_{z} \\ \gamma_{yz} \\ \gamma_{zx} \\ \gamma_{xy} \end{pmatrix}$$

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Stiffness and Compliance

- The matrix of stiffness coefficients, analogous to Young's modulus, are denoted by Cij
- The matrix of compliance coefficients, which is the inverse of Cij, is denoted by Sij
- > Yes, the notation is cruel
- Some texts use different symbols, but these are quite widely used in the literature

$$\sigma_{I} = \sum_{J} C_{IJ} \varepsilon_{J}$$
and
$$\varepsilon_{I} = \sum_{J} S_{IJ} \sigma_{J}$$

Cubic materials

> Only three independent elastic constants

- C11 = C22 = C33
- C12 = C23 = C31 = C21 = C32 = C13
- C44 = C55 = C66
- All others zero
- > Values for silicon
 - C11 = 166 GPa
 - C12 = 64 GPa
 - C44 = 80 GPa

$$egin{pmatrix} C_{11} & C_{12} & C_{12} & 0 & 0 & 0 \ C_{12} & C_{11} & C_{12} & 0 & 0 & 0 \ C_{12} & C_{12} & C_{11} & 0 & 0 & 0 \ 0 & 0 & 0 & C_{44} & 0 & 0 \ 0 & 0 & 0 & 0 & C_{44} & 0 \ 0 & 0 & 0 & 0 & 0 & C_{44} \ \end{pmatrix}$$

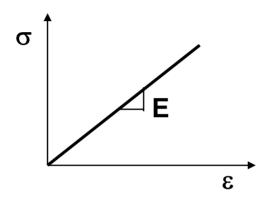
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Materials with Lower Symmetry

- > Examples:
 - Zinc oxide 5 elastic constants
 - Quartz 6 elastic constants
- > These materials come up in piezoelectricity
- > Otherwise, we can enjoy the fact that most materials we deal with are either isotropic or cubic

What lies beyond linear elasticity?

> So far, we have assumed linear elasticity.



- > Linear elasticity fails at large strains
 - Some of the deformation becomes permanent (plastic strain)
 - Things get stiffer
 - Things break

Plastic deformation

- Beyond the yield point, a plastic material develops a permanent set
- This is exploited in the bending and stamping of metals

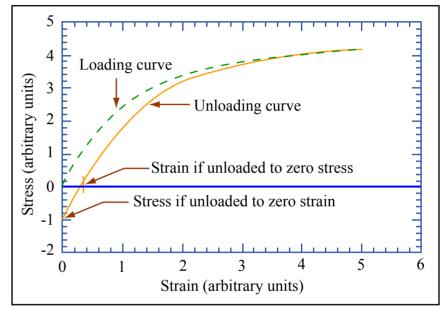


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Adapted from Figure 8.8 in: Senturia, Stephen D. *Microsystem Design*. Boston, MA: Kluwer Academic Publishers, 2001, p. 198. ISBN: 9780792372462.

Material behavior at large strain

> Brittle and ductile materials are very different

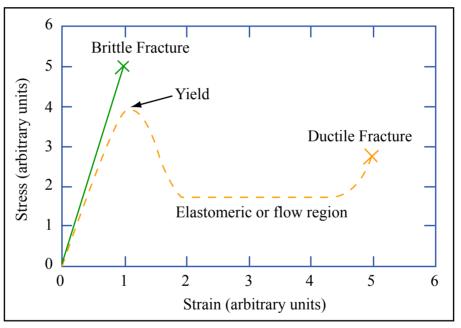


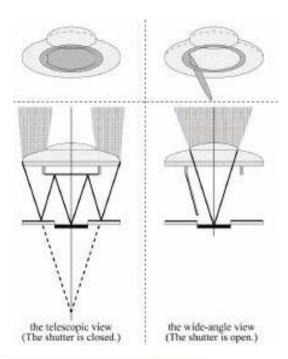
Image by MIT OpenCourseWare.

Adapted from Figure 8.7 in: Senturia, Stephen D. *Microsystem Design*. Boston, MA: Kluwer Academic Publishers, 2001, p. 197. ISBN: 9780792372462.

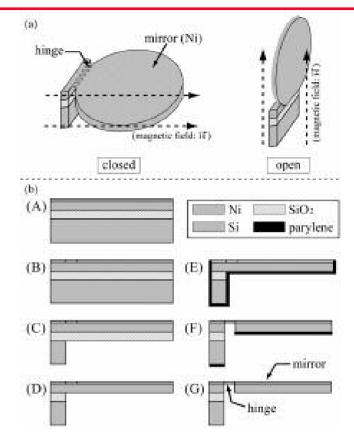
Cite as: Carol Livermore, course materials for 6.777J / 2.372J Design and Fabrication of Microelectromechanical Devices, Spring 2007. MIT OpenCourseWare (http://ocw.mit.edu/), Massachusetts Institute of Technology. Downloaded on [DD Month YYYY].

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Any thoughts on this device?







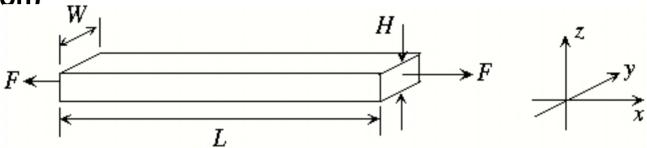
Figures 2, 3, and 4 on pp. 236-237 in: Kinoshita, H., K. Hoshino, K., K. Matsumoto, and I. Shimoyama. "Thin Compound eye Camera with a Zooming Function by Reflective Optics." In *MEMS 2005 Miami: 18th IEEE International Conference on Micro Electro Mechanical Systems: technical digest, Miami Beach, Florida, USA, Jan. 30-Feb. 3, 2005.* Piscataway, NJ: IEEE, 2005, pp. 235-238. ISBN: 9780780387324. © 2005 IEEE.

Outline

- > Overview
- > Some definitions
 - Stress
 - Strain
- > Isotropic materials
 - Constitutive equations of linear elasticity
 - Plane stress
 - Thin films: residual and thermal stress
- > A few important things
 - Linear elasticity in anisotropic materials
 - Behavior at large strains
- Using this to find the stiffness of structures

A simple example: axially loaded beams

> In equilibrium, force is uniform; hence stress is inversely proportional to area (as long as area changes slowly with position) ...



Geometry:

$$\sigma = \frac{F}{A} = \frac{F}{WH}$$
 and $\varepsilon = \frac{\Delta L}{L}$

Uniaxial stress:

$$\sigma = \varepsilon E$$

$$\frac{F}{WH} = E \frac{\Delta L}{L}$$

$$F = \frac{EWH}{L} \Delta L$$

$$F = k\Delta L \implies k = \frac{EWH}{L}$$

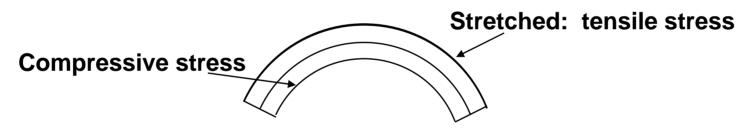
Plug in for L=100 μ m, W=5 μ m, H=1 μ m, E=160 GPa:

k=8000 N/m

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Another example: bending of beams and plates

- > Stress and strain underlie bending, too
- Unlike uniaxial tension, where stress and strain are uniform, bending of beams and plates is all about how the spatially varying stress and strain contribute to an overall deformation.



> Next time!